

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: **Sun, et al.**

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Case: AMAT/8241/CMP/ECP/RKK

Serial No.: 10/616,097

Filed: July 8, 2003

Examiner: **Edna Wong**

Group Art Unit: 1753

Confirmation No.: 1645

**Title: MULTIPLE-STEP
ELECTRODEPOSITION PROCESS
FOR DIRECT COPPER PLATING ON
BARRIER MATERIALS**

MAIL STOP Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

RESPONSE TO OFFICE ACTION DATED MARCH 13, 2008

In response to the Office Action dated March 13, 2008 having a shortened statutory period for response set to expire on June 13, 2008, please enter this response and reconsider the claims pending in the application for the reasons discussed below. Although the Applicants believe that no fee is due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782 for any other fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.